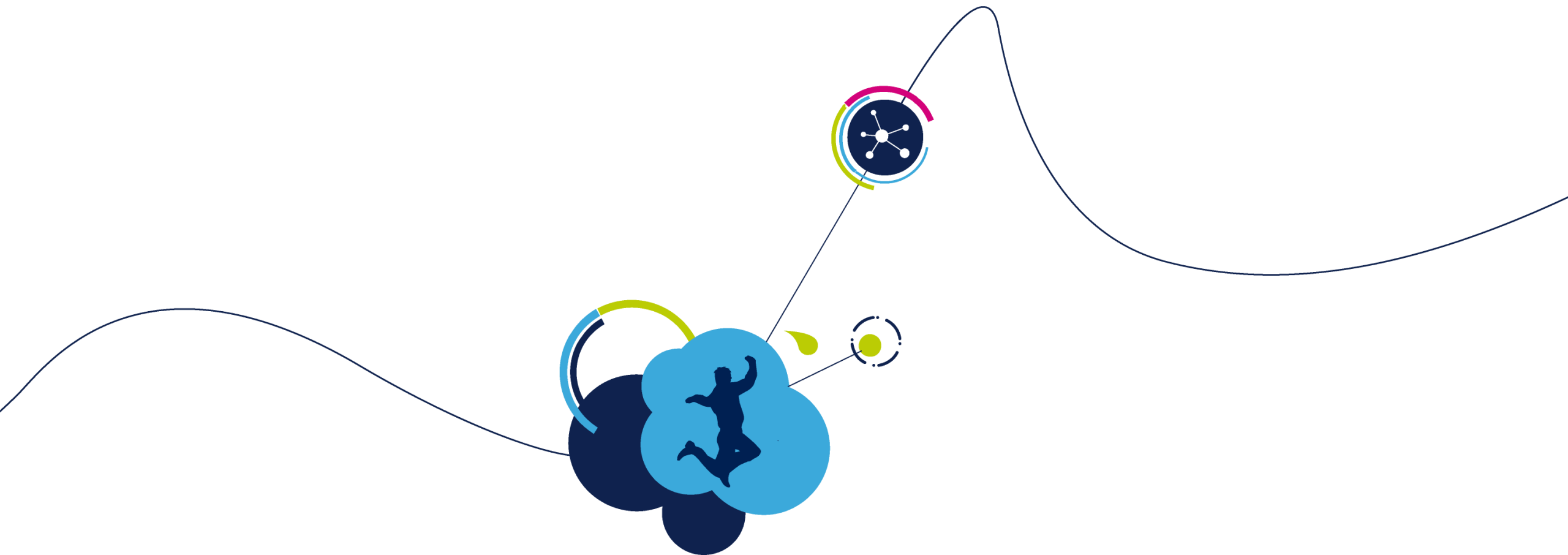


# SiC MOSFETs Enable Electric Vehicles with Enhanced Performance

Jeff Fedison, Ph.D.  
Sr. Applications Engineer



1. SiC technology
2. SiC Power MOSFETs
3. Traction inverter example: SiC MOSFET versus Si IGBT
4. Latest advances
5. Conclusion



# SiC Technology

# What is Silicon Carbide?

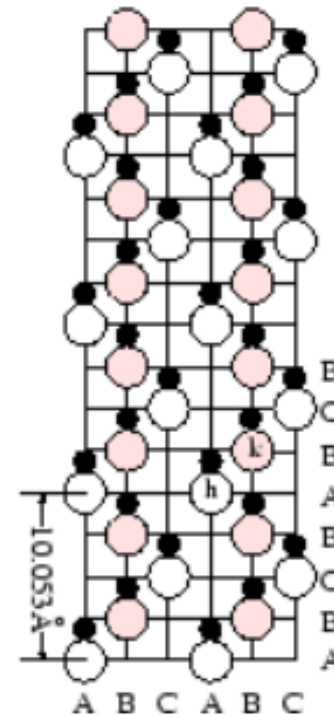
4

- 4H-SiC and 6H-SiC are both commercially available
- 4H-SiC is most important for power electronics

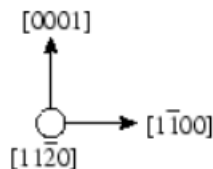
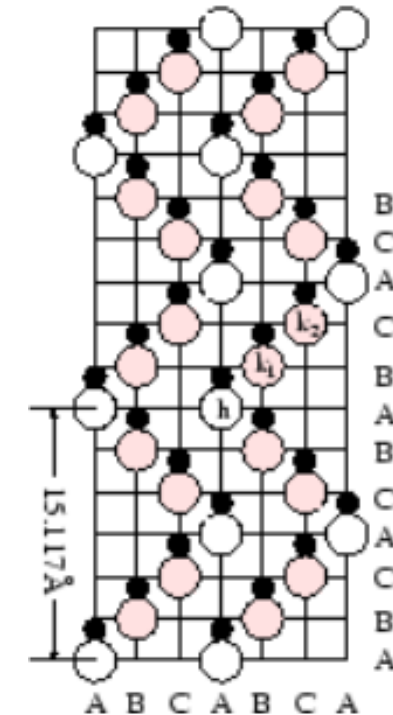
## 4H-SiC

- Is a wide bandgap semiconductor material
- Remains a solid up to 2830°C
- Is available in semiconductor grade wafers up to 6 inches in diameter

4H-SiC



6H-SiC



# What makes 4H-SiC useful for Power Electronics?

5

- Can be doped both p-type and n-type
- High electron mobility
- $\text{SiO}_2$  is native oxide
- 3x higher thermal conductivity vs Si
- Large band gap energy allows very high temperature operation
- **High critical electric field, 10x that of silicon!**

# Wide Bandgap Materials

6

## Radical innovation for Power Electronics

	Si	GaN	4H-SiC
$E_g$ (eV) – Band gap	1.1	3.4	3.3
$V_s$ (cm/s) – Electron saturation velocity	$1 \times 10^7$	$2.2 \times 10^7$	$2 \times 10^7$
$\epsilon_r$ – dielectric constant	11.8	10	9.7
$E_c$ (V/cm) – Critical electric field	$3 \times 10^5$	$2.2 \times 10^6$	$2.5 \times 10^6$
$k$ (W/cm K) thermal conductivity	1.5	1.7	5

$E_c$  → low on resistance

$E_g$  → low leakage, high  $T_j$

$k$  → Operation > 200 °C  
Reduced Cooling Requirements

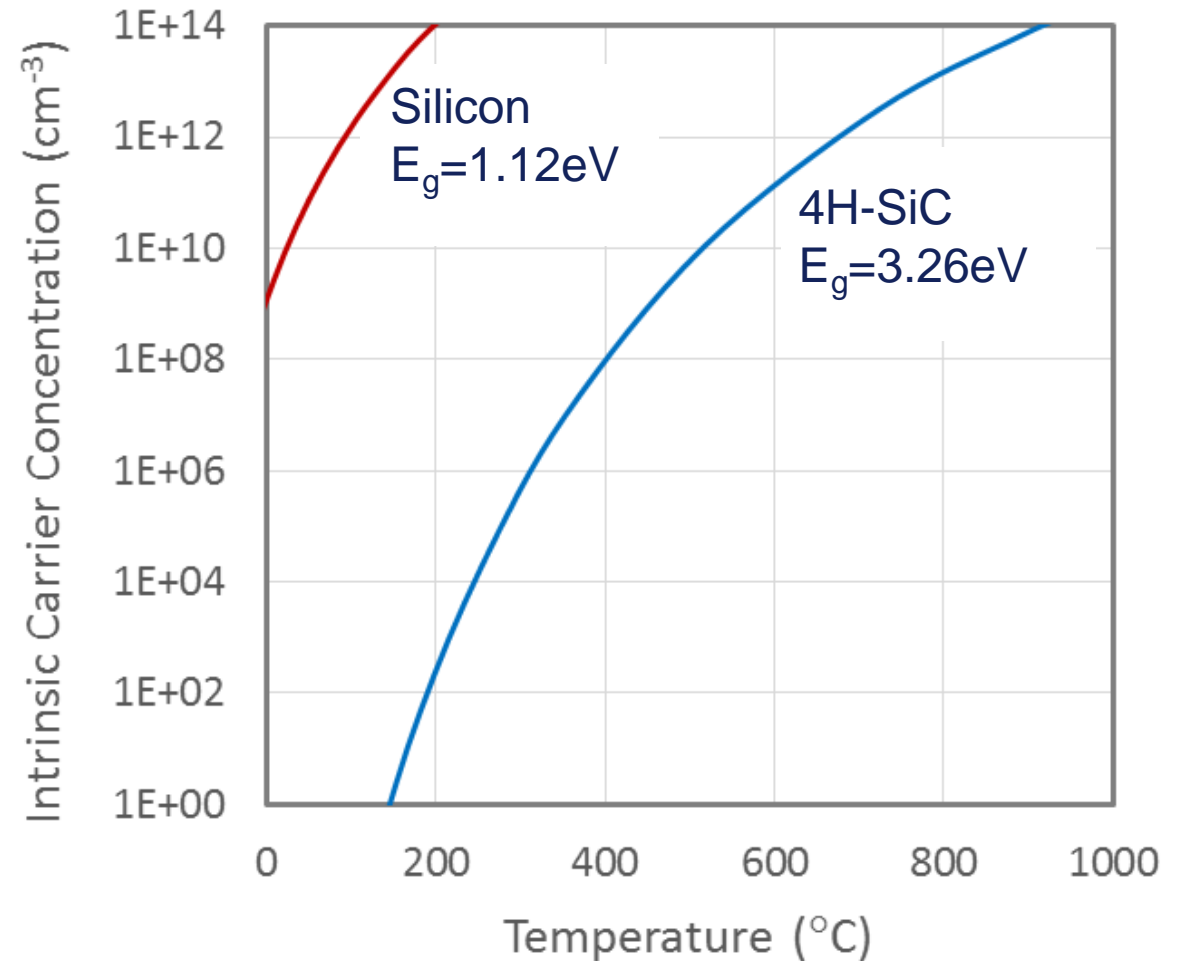
$V_s$  → Higher switching frequency  
Lower switching losses

# Intrinsic carrier concentration, $n_i$

## SiC vs. Silicon

7

- Intrinsic carriers are thermally generated and increase in number at higher temperatures
- Because of its larger band gap energy, SiC maintains low intrinsic carrier concentration up to 900°C



# SiC provides low reverse leakage current up to high temperature

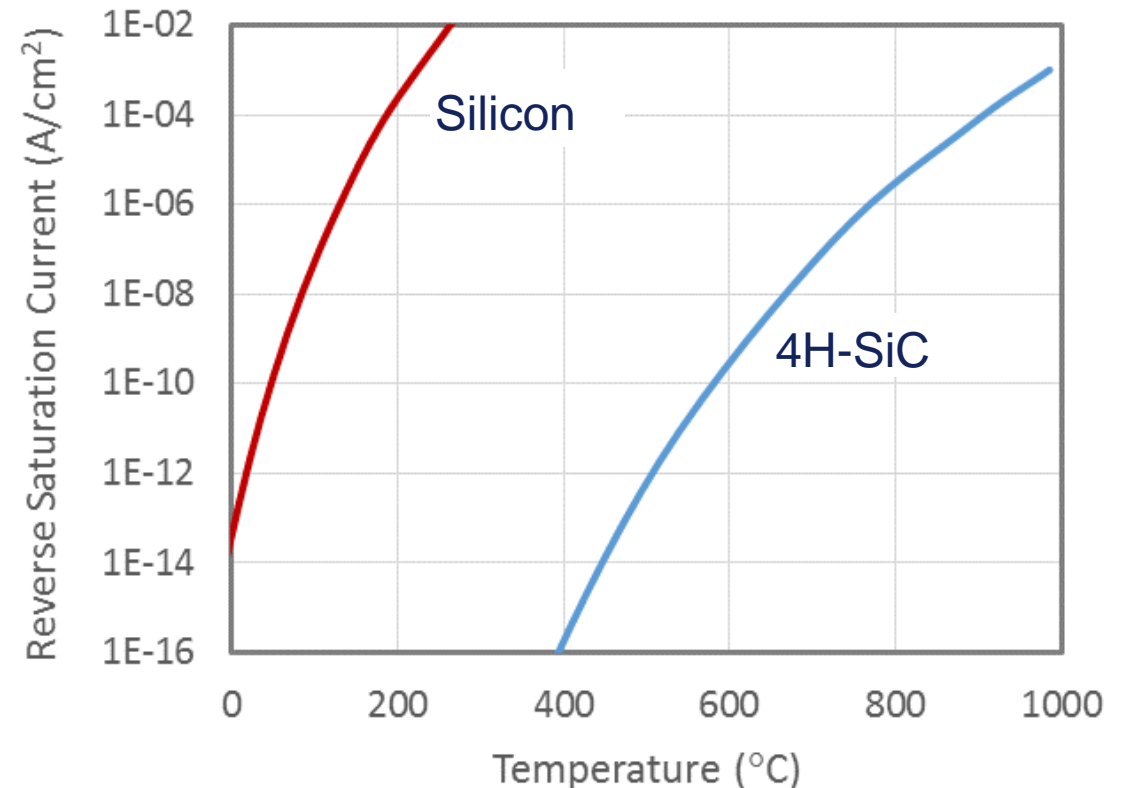
8

Reverse saturation current of a p<sup>+</sup>n diode:

$$J_S = q n_i^2 \left( \frac{1}{N_D} \sqrt{\frac{D_p}{\tau_p}} \right)$$

- Silicon becomes unusable above ~ 250°C due to high leakage current
- 4H-SiC has low reverse leakage current up to 900°C

Reverse saturation current for 1200V p<sup>+</sup>n diode

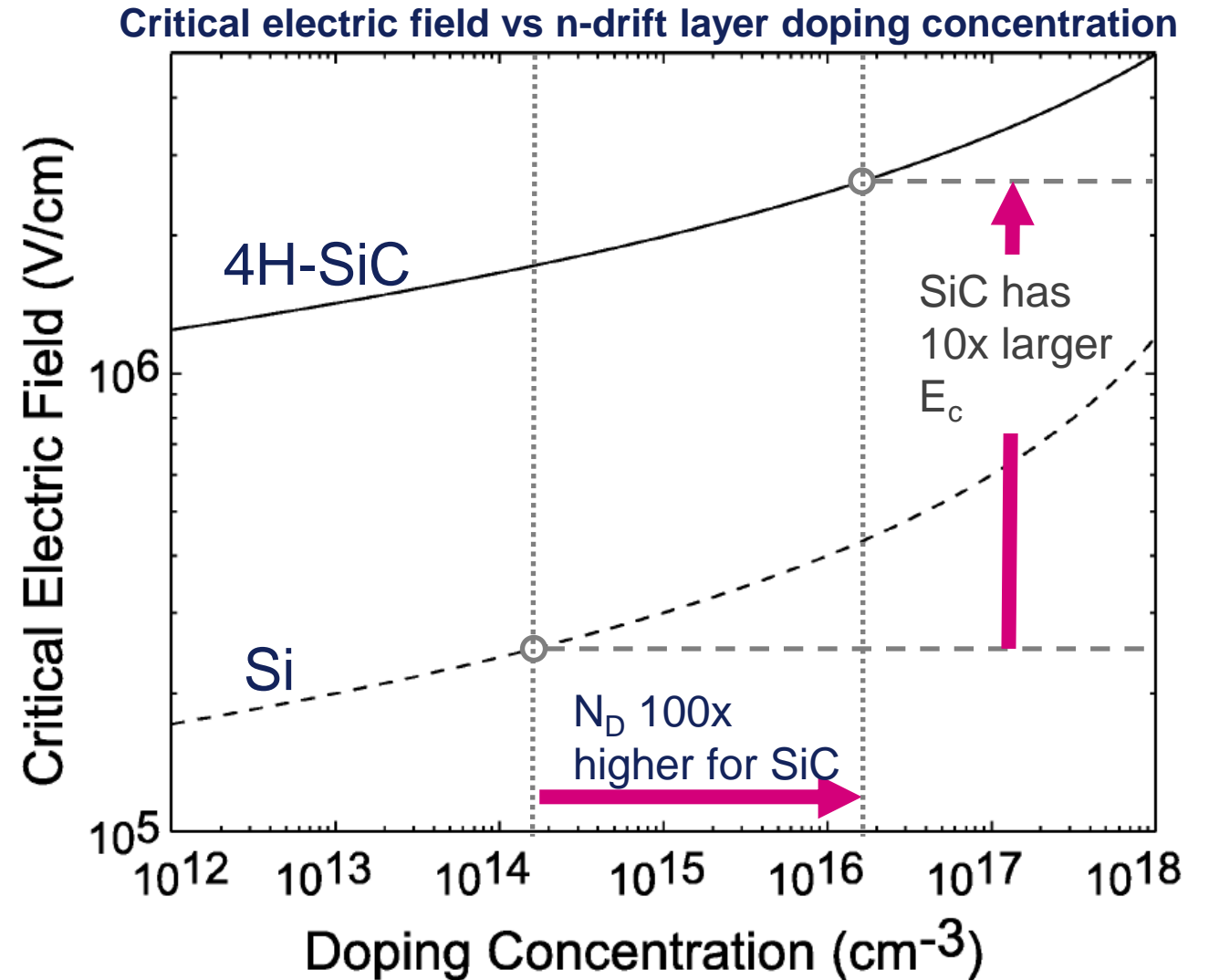




# Critical electric field 9

- For a given breakdown voltage, the larger critical electric field of SiC enables much higher drift layer doping vs Si

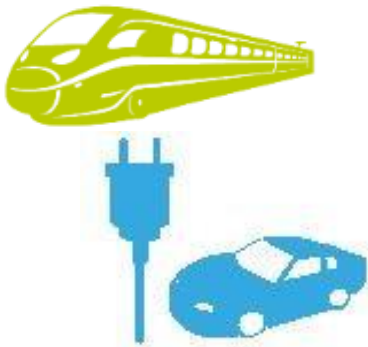
Material	Drift layer doping for BV=1200V
Si	$1.5 \times 10^{14} \text{ cm}^{-3}$
SiC	$1.6 \times 10^{16} \text{ cm}^{-3}$



Note: circles show  $N_D$  required for 1200V NPT design

# Key Applications for SiC

10



HEV/EV &  
Traction



SMPS  
& PFC



Solar  
Inverter



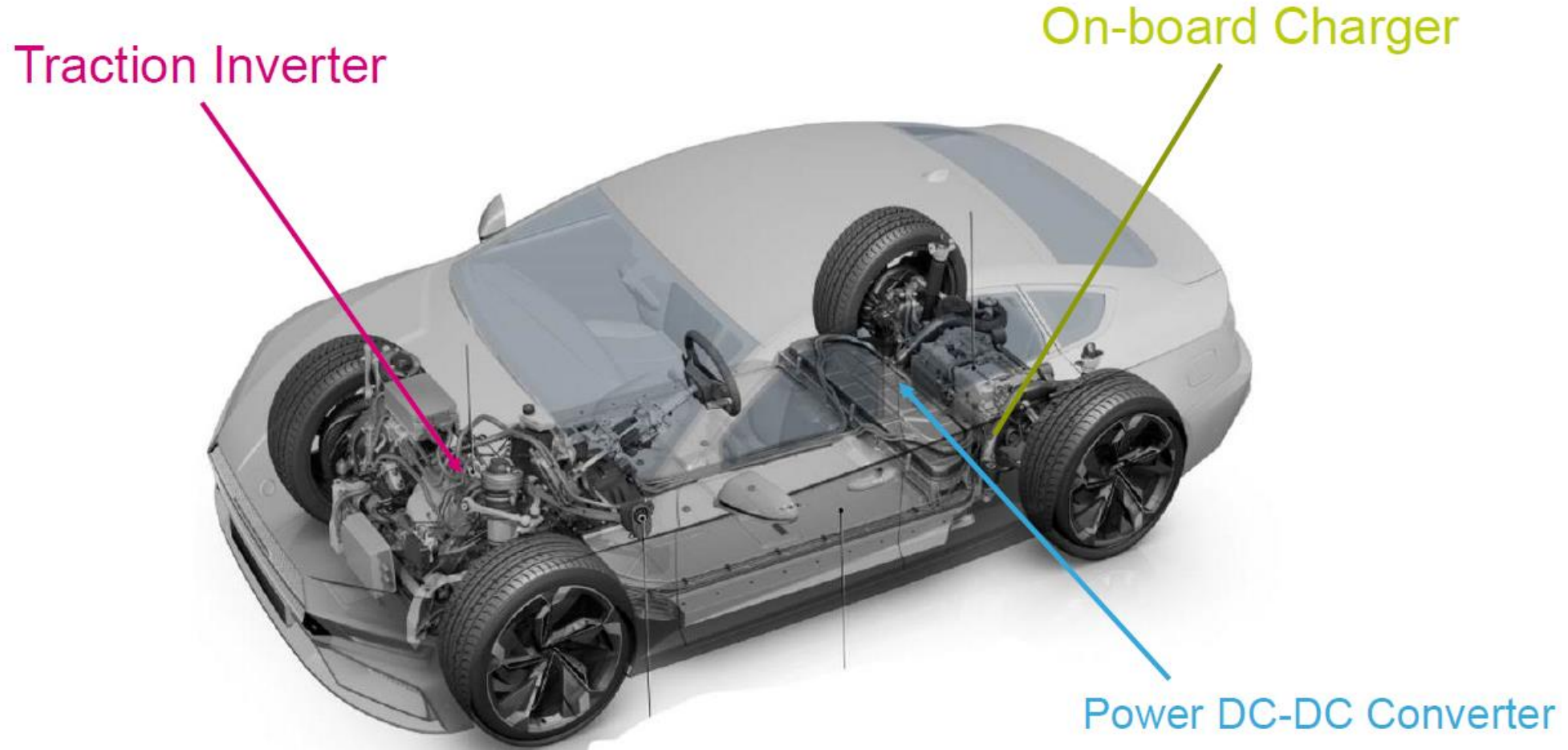
OBC &  
Charging  
station



Industrial  
Drives

# Where is Silicon Carbide Being Used in Electric Vehicles?

11

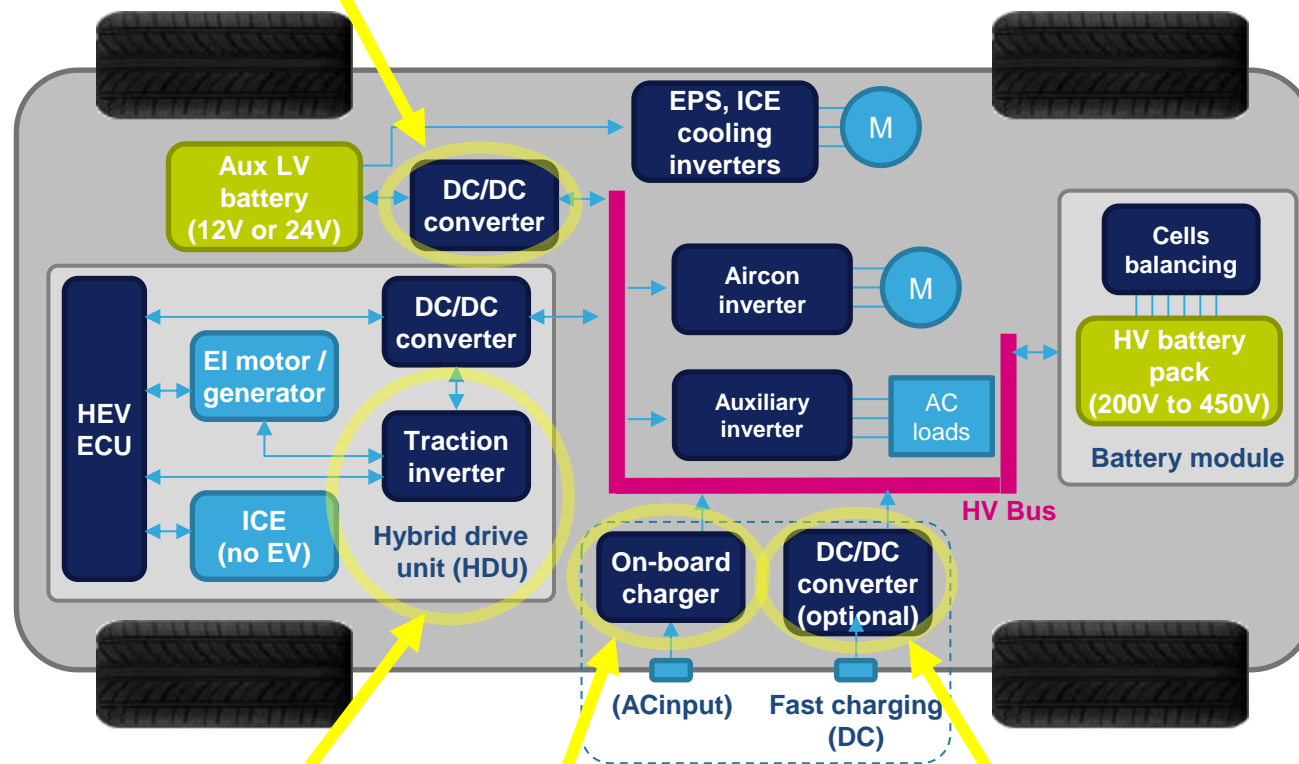





# e-Vehicle block diagram

12

HEV/EV

Output Power: **4kW**  
IGBT → SiC MOSFET  
50kHz – 200kHz



-  Silicon content
-  Mechanical or electro-mechanical
-  Batteries

Output Power (EV): **80kW — 250kW**  
IGBT → SiC MOSFET  
12kHz and higher

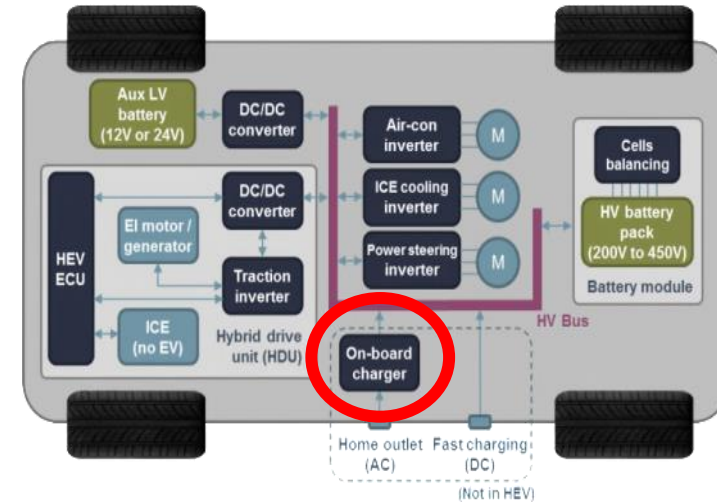
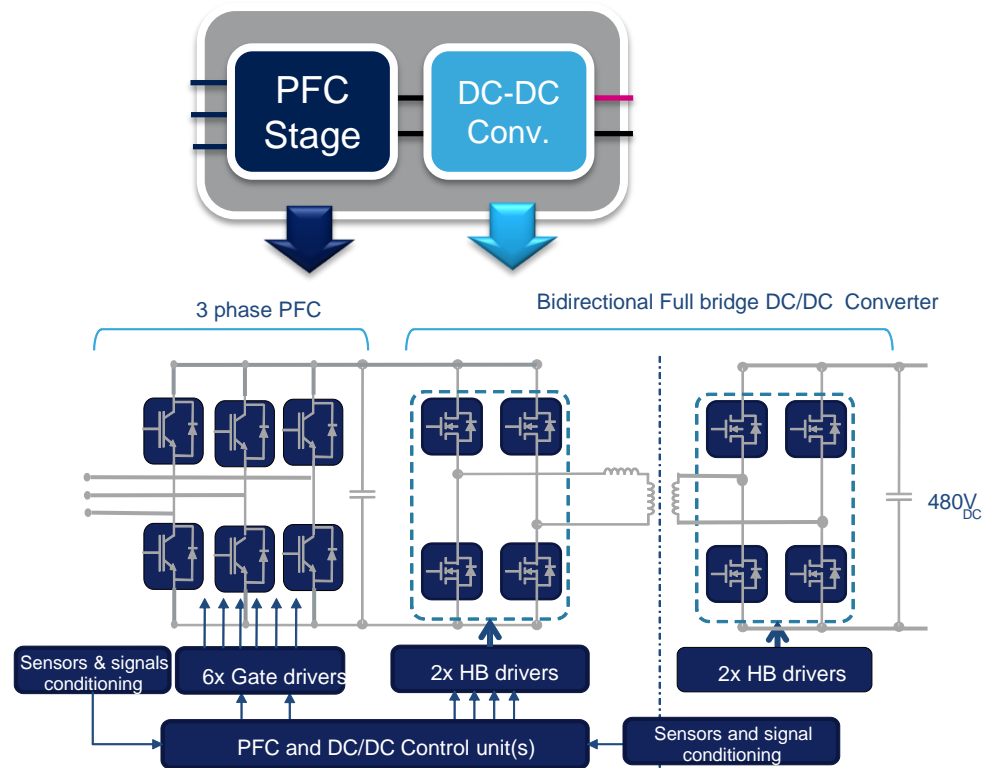
Output Power: **20kW**  
SiC MOSFET/SiC SBD  
50kHz – 200kHz

Output Power: **50kW**  
Si MOSFET → SiC MOSFET  
50kHz – 200kHz



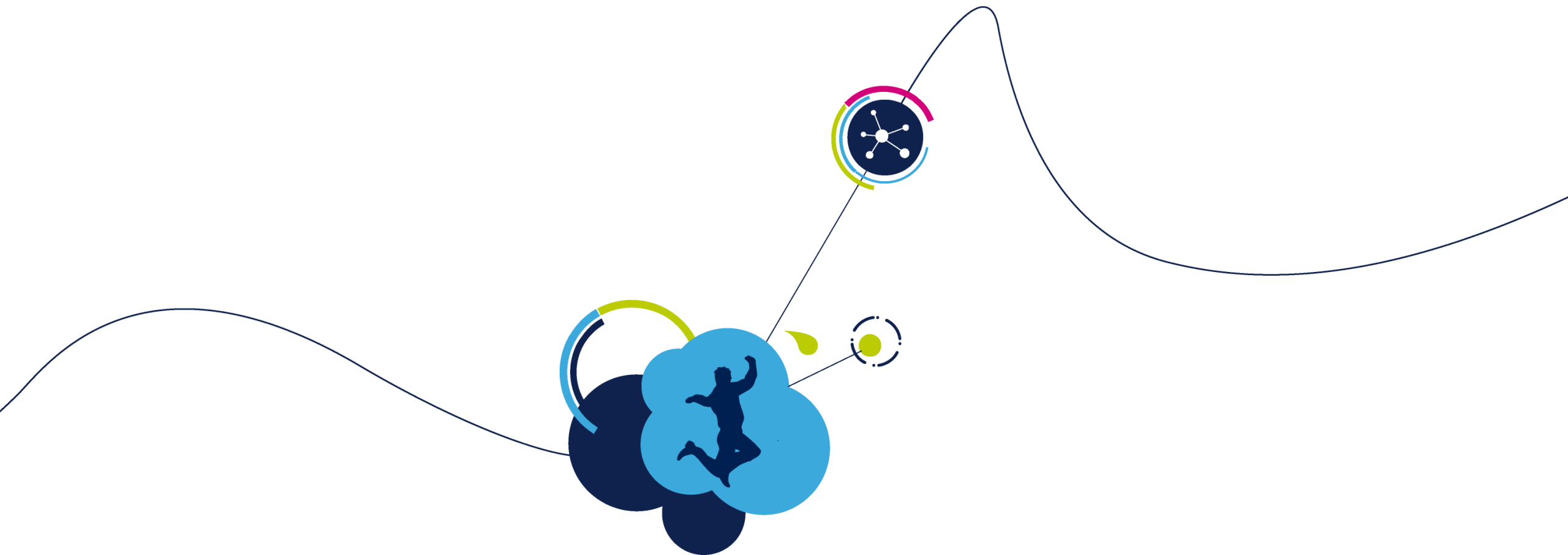
# Battery charger for HEV/EV

14



Single-phase architecture → SiC MOS 650V

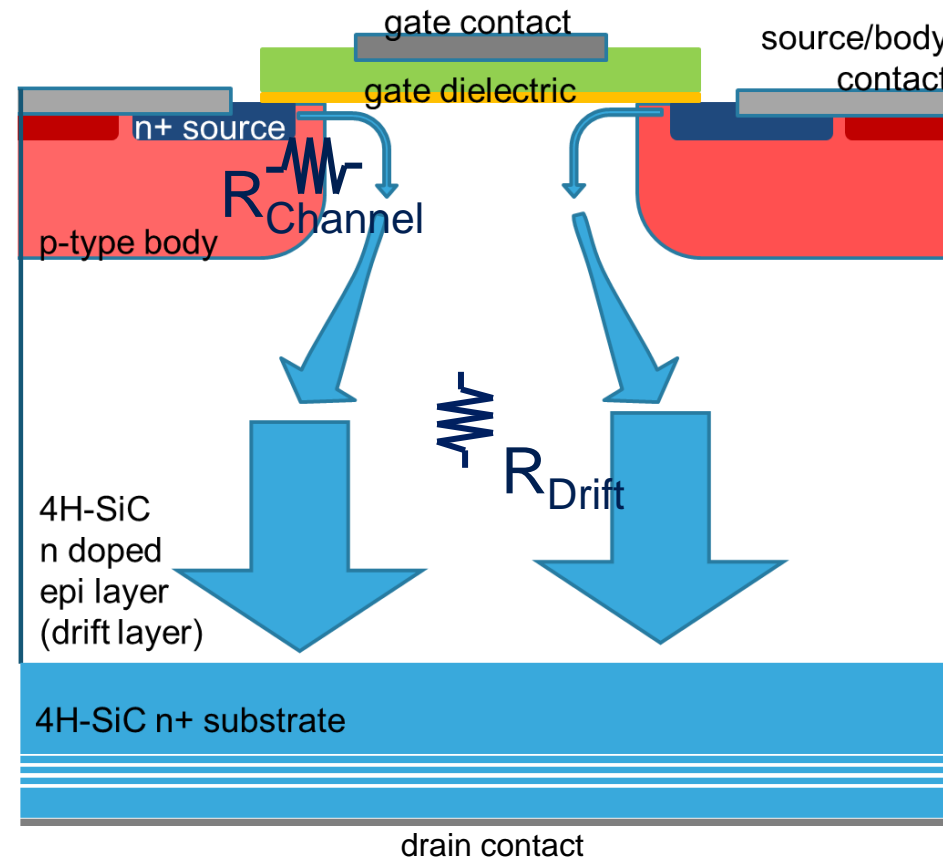
Three-phase architecture → mainly SiC MOS 1200V



# SiC Power MOSFETs

# High-Voltage DMOSFET Structure

16



$R_{DS(on)}$  is determined mainly by  $R_{Drift}$  and to lesser extent  $R_{Channel}$



# Drift layer dimensions for 1200V DMOSFET

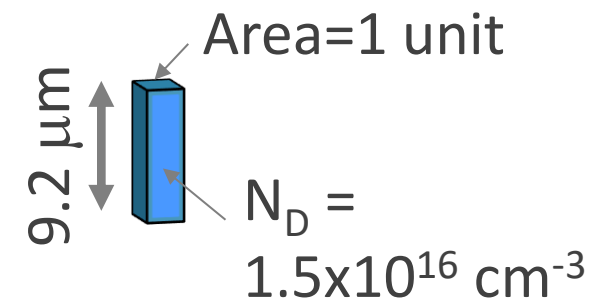
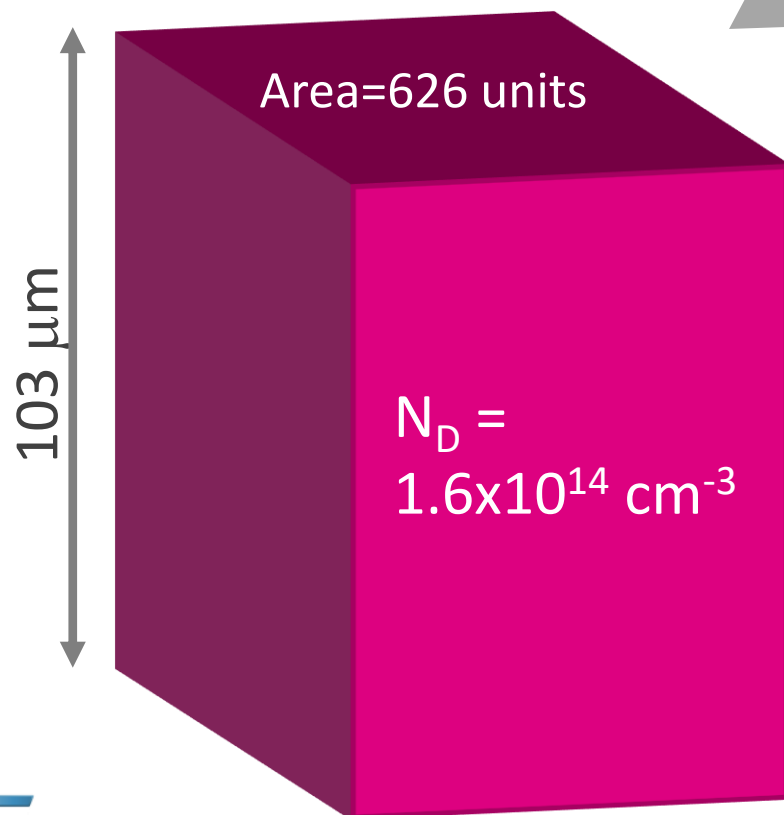
17

SiC vs. Silicon

**Silicon**

**SiC**

for columns  
of equal  
resistance



For equal drift layer resistance at  $T_j=25\text{C}$ :

$$\text{AREA: SiC} = \frac{1}{626} \text{ Silicon}$$

$$\text{THICKNESS: SiC} = \frac{1}{11} \text{ Silicon}$$

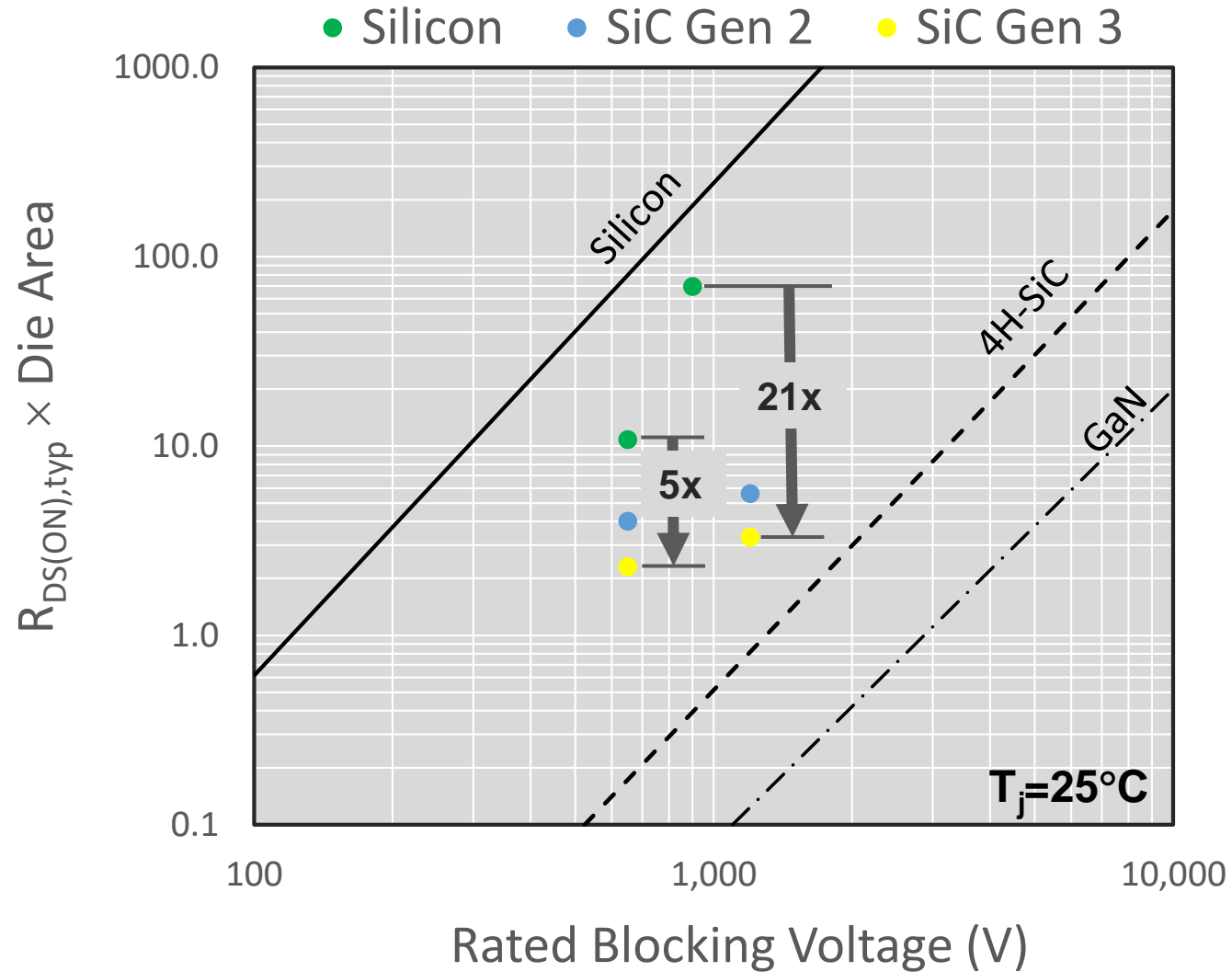
$$\text{CAPACITANCE: SiC} = \frac{1}{46} \text{ Silicon}$$

$$\text{THERMAL RESISTANCE: SiC} = 17 \text{ Silicon}$$

SiC offers dramatic reduction in device footprint!

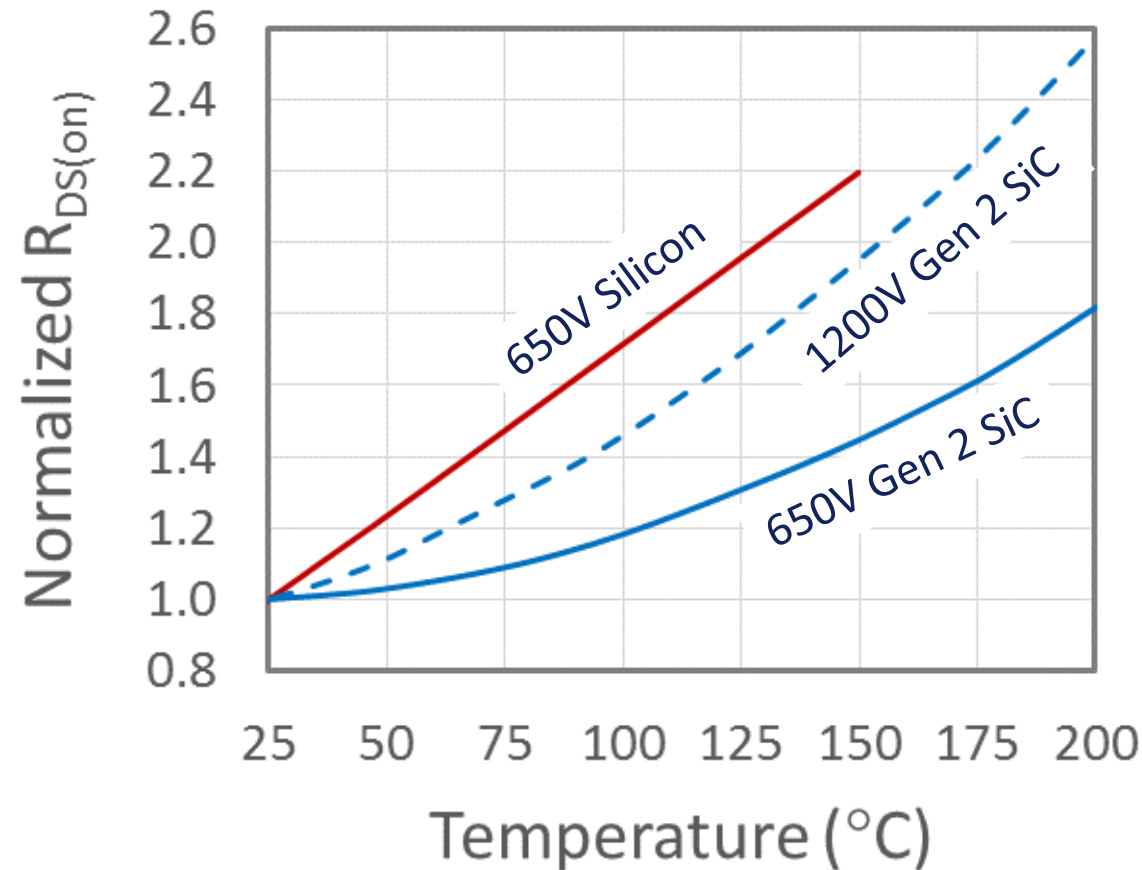
# MOSFET $R_{DS(on)} \times \text{Area}$ Figure of Merit

18



# $R_{DS(on)}$ variation with temperature

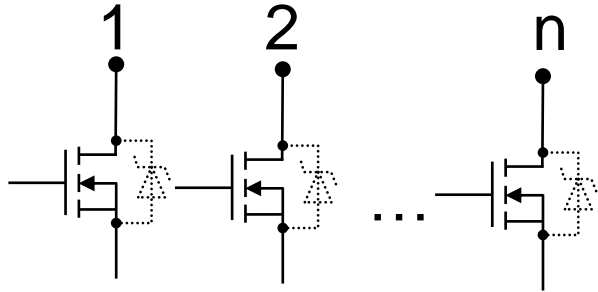
19



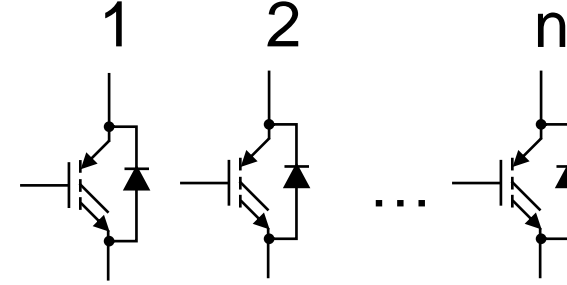
ST is the only supplier to guarantee max  $T_j$  as high as 200 $^{\circ}\text{C}$  in plastic package

# SiC MOSFET Allows Lowest Conduction Losses

20

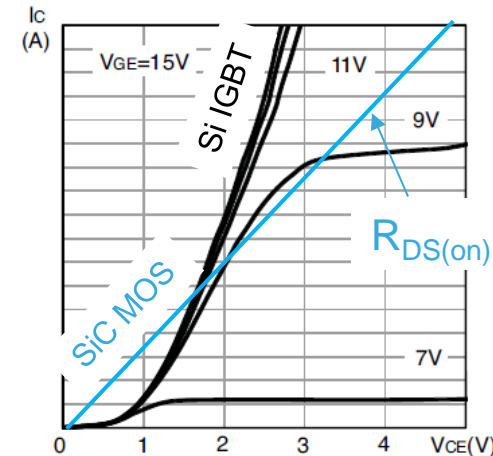


When “n” MOSFETs are paralleled the total  $R_{DS(on)}$  is divided by “n” allowing very low conduction losses



When “n” IGBTs are paralleled the  $V_{ce(sat)}$  doesn't decrease linearly but reaches a limiting voltage drop of about 0.8V as n increases.

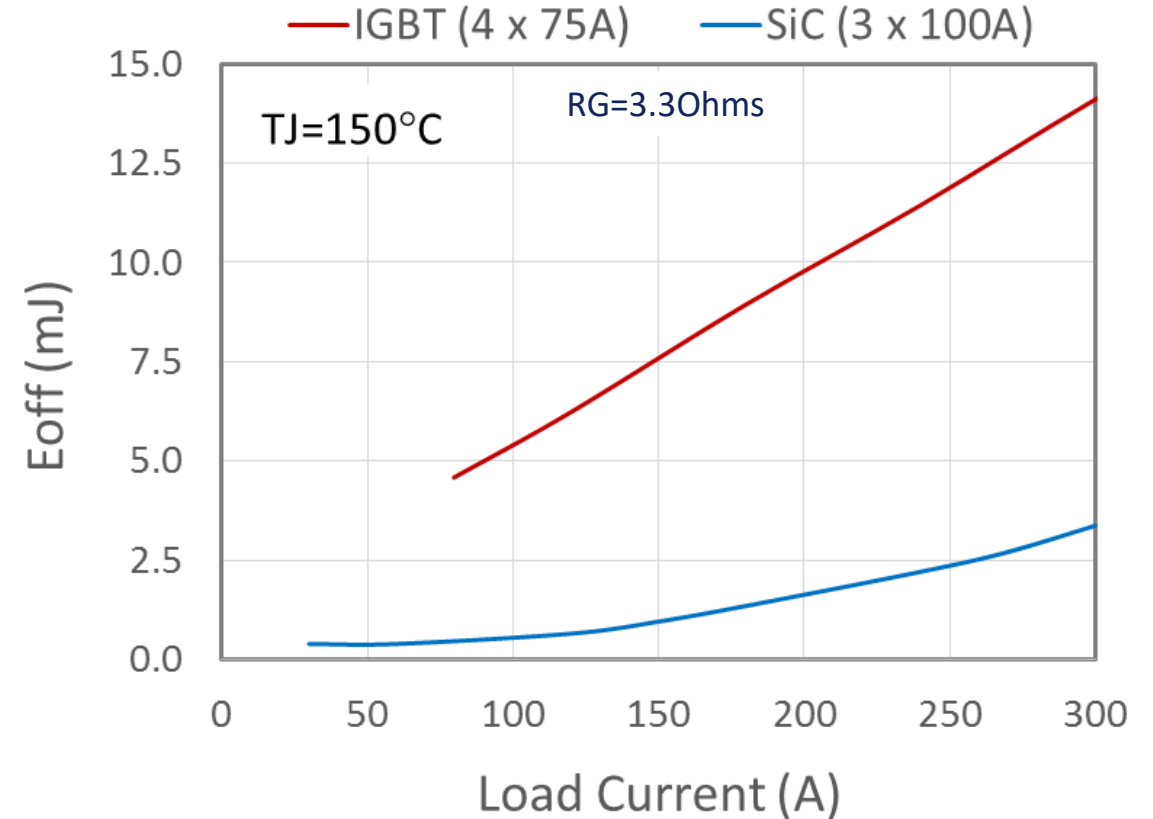
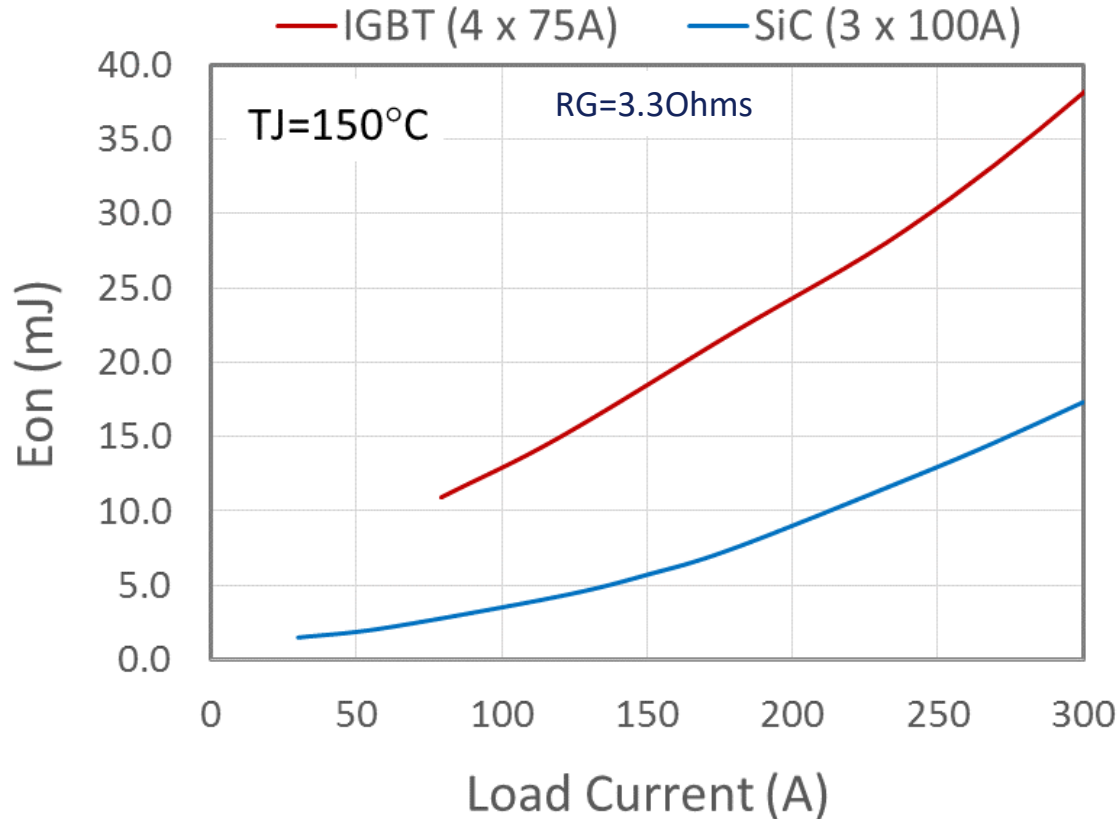
The lowest possible conduction losses can be achieved only with MOSFETs



# Switching energies for 1200V rated devices

IGBT vs SiC MOSFET

21



# Benefits of SiC MOSFETs

22

## Key Benefits



### Extremely low Switching Losses and Ultra-Low $R_{DS(on)}$

Higher operating frequency for smaller and lighter systems



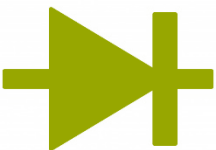
### Good Thermal Performance

High operating temperature (  $T_{jmax} = 200^{\circ}C$  )  
Reduced cooling requirements & heat-sink, Increased lifetime



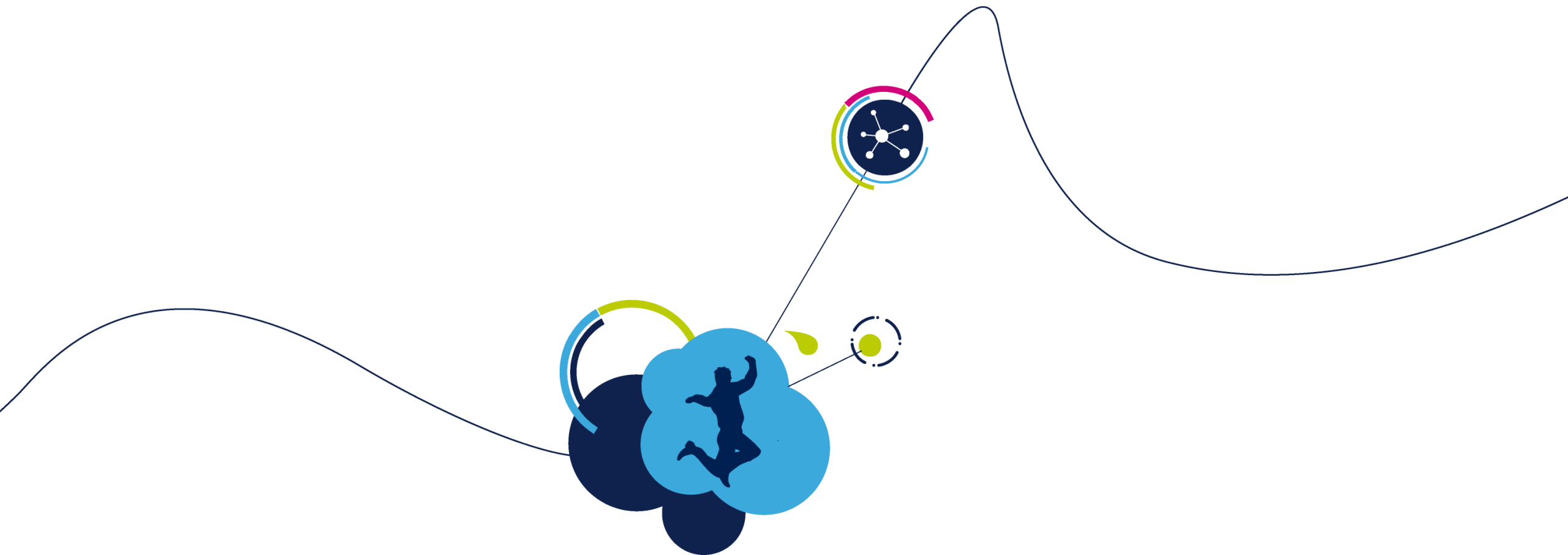
### Easy to Drive

Fully compatible with standard Gate Drivers



### Very fast and robust intrinsic body diode

Separate antiparallel diode not required



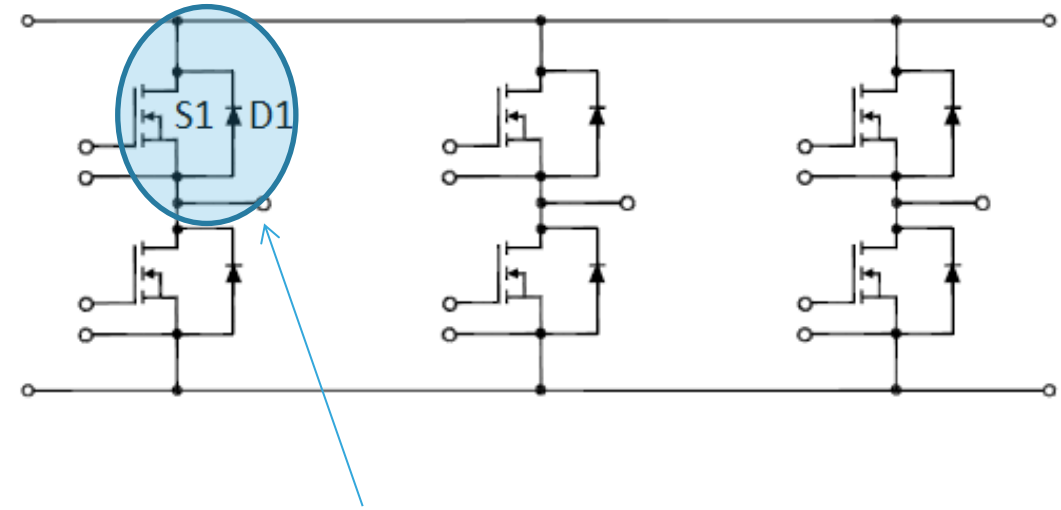
# 80kW EV Traction Inverter Power Loss Estimation:

1200V Gen 3 SiC MOSFETs vs 1200V Si IGBT + Diode

# Operating conditions

24

- Topology: Three phase inverter
- Bipolar PWM Strategy
- Synchronous rectification (SiC version)
- DC-link voltage:  $800V_{dc}$
- Current 250Arms (peak) 120Arms (nom)
- Switching frequency: 16kHz
- $V_{gs}=+18V/-5V$  for SiC,  $V_{ge}=\pm 15V$  for IGBT
- $\cos(\phi)$ : 0.8
- Modulation index (MI): 1
- Cooling fluid temperature:  $65^{\circ}C$
- $R_{thJ-C(IGBT-die)}=0.19^{\circ}C/W$ ;  
 $R_{thJ-C(SiC-die)}=0.30^{\circ}C/W$
- $T_j \leq 80\% * T_{jmax}^{\circ}C$  at any condition



**Si IGBT requires  
antiparallel diode, SiC  
MOSFET does not**

**Switch (S1+D1) implementation**

**4 x 1200V, 75A IGBTs + 4 x 1200V, 75A Si diodes  
vs.  
3 x 1200V, 100A SiC MOSFETs SCT110G3D2AG**



# Power loss at peak condition

25

$f_{sw}=16\text{kHz}$ ,  $250\text{A}_{rms}$  (10sec)

\* Typical power loss values

Loss Energy	Si-IGBT + Si-diode Solution	Full-SiC Solution	SiC vs Si per switch (S1+D1)
Total chip-area	180 mm <sup>2</sup> (IGBT) + 90 mm <sup>2</sup> (diode)	78 mm <sup>2</sup>	3.5x smaller area
Conduction losses* (W)	196.2	256.1	
Switching losses* (W)	316.6	94.0	3.4x lower
Diode's conduction losses* (W)	58.3	49.0	
Diode's $Q_{rr}$ losses* (W)	91.1	6.4**	
(S1+D1) Total losses* (W)	662.2	405.6	40% lower
Junction Temperature (°C)	134.2	151.5	$T_J < 80\% T_{jmax}$

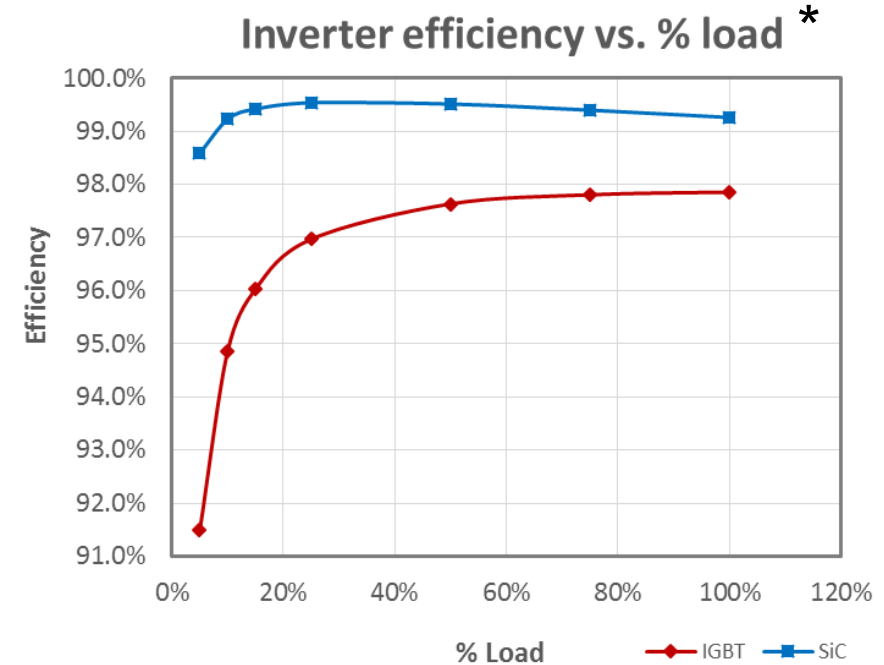
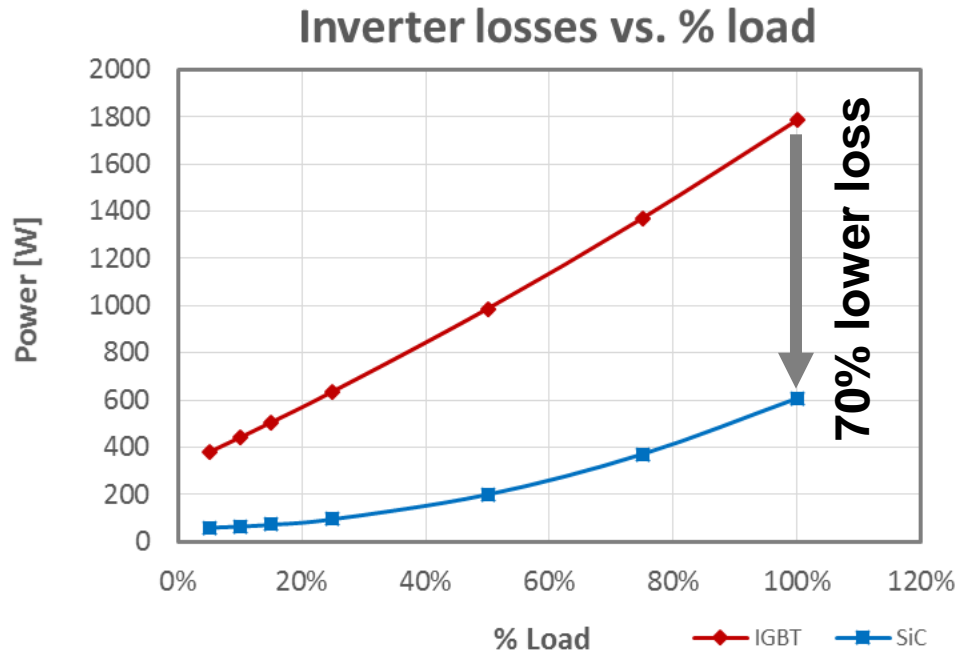
\*\* Assuming  $di/dt = 2000 \text{ A}/\mu\text{s}$  at  $I_{SD}=50\text{A}$

**SiC MOSFET runs at higher junction temperature in spite of lower losses.  
This is due to the exceptional SiC  $R_{DS(on)} \times \text{Area}$  FOM.**

# SiC Solution: lower losses, higher efficiency

26

$f_{sw}=16\text{kHz}$ , 100% load:  $120\text{A}_{rms}$  (80kW)



**SiC shows much lower loss over the whole load range**

**SiC offers 1.4% higher efficiency or more over the whole load range!**

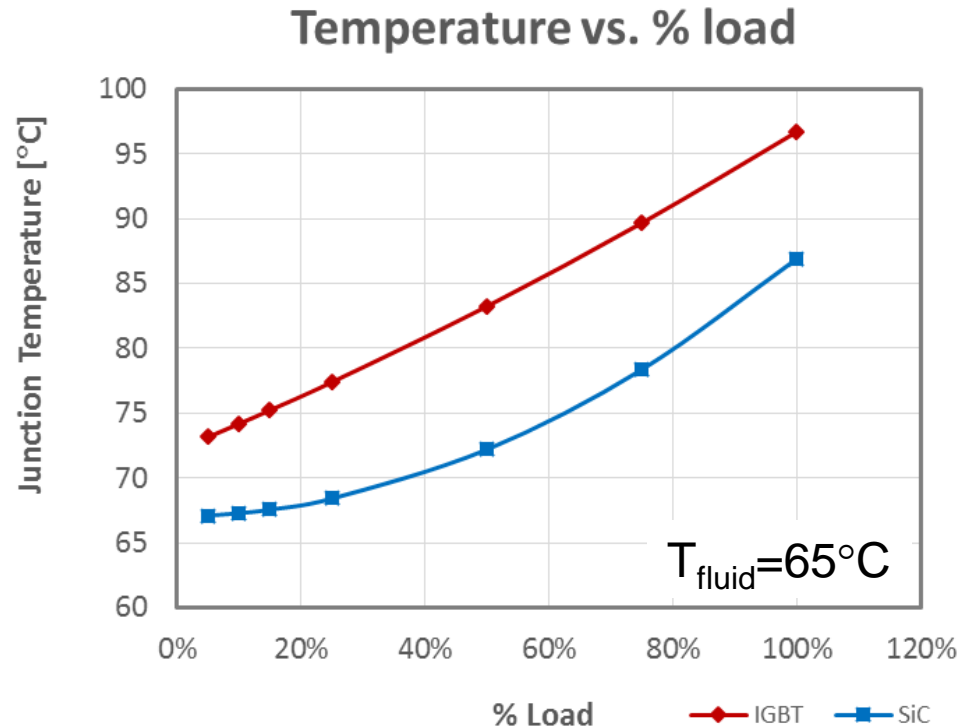
**Lower losses mean smaller cooling system and longer battery autonomy**

\* The simulated efficiency takes into account only the losses due to the switches and diodes forming the bridge inverter

# Remarks about junction temperature

27

$f_{sw}=16\text{kHz}$ , 100% load:  $120\text{A}_{rms}$  (80kW)



- $R_{th,JC(IGBT-die)}=0.19^{\circ}\text{C/W}$
- $R_{th,JC(SiC-die)}=0.30^{\circ}\text{C/W}$

Heat sink:

- $R_{th,CA}=0.35^{\circ}\text{C/W}$

**SiC solution is better than Silicon in reliability since SiC has lower  $\Delta(T_j-T_{fluid})$  up to 100% load.**

# SiC MOSFET enables EV cost savings

28

## Battery cost savings

- SiC inverter is 3.4% more efficient vs. IGBT inverter at average EV operating condition (15% load)
- Compared to IGBT based EV with 85kWh battery, SiC version requires only 82.1kWh for same range
- Typical battery cost: \$150 per kWh
- **Battery cost savings with SiC based inverter (this example) : \$435**

## Heat sink considerations

Heat sink must be sized according to power dissipation at maximum operating condition

Inverter dissipation at peak load (250Arms):

	IGBT	SiC MOSFET
Power Dissipation	3973W	2434W

SiC based inverter will only need to dissipate **61% of the heat** compared to IGBT version

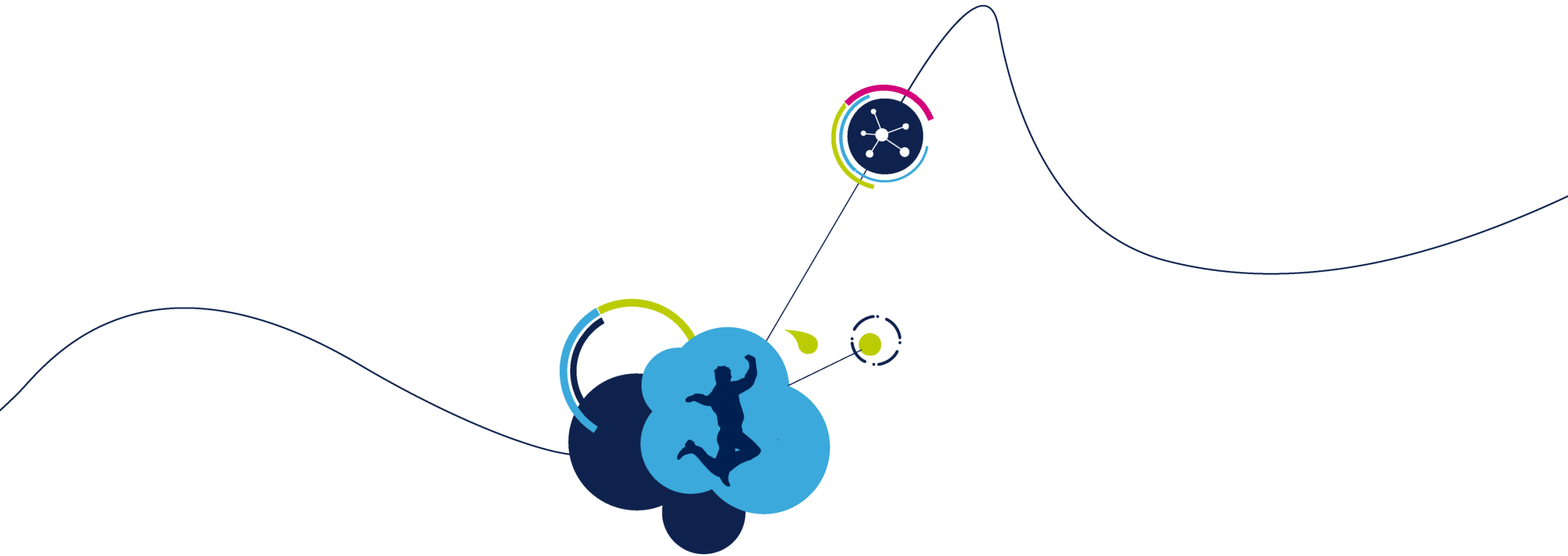
**→ SiC MOSFET allows smaller, lower cost heatsink**

# SiC MOSFET traction inverter

## Key advantages

29

- More than 50% module/package size reduction
  - Much smaller semiconductor area giving ultra-compact solution
- >1.4% efficiency improvement and 70% lower loss at full load:
  - Much lower loss at low load allows smaller battery for same range
- 40% cooling system downsize:
  - Lower losses at full load giving smaller cooling system
  - Lower  $\Delta T$  ( $T_j - T_{\text{fluid}}$ ) in the whole load range giving better reliability



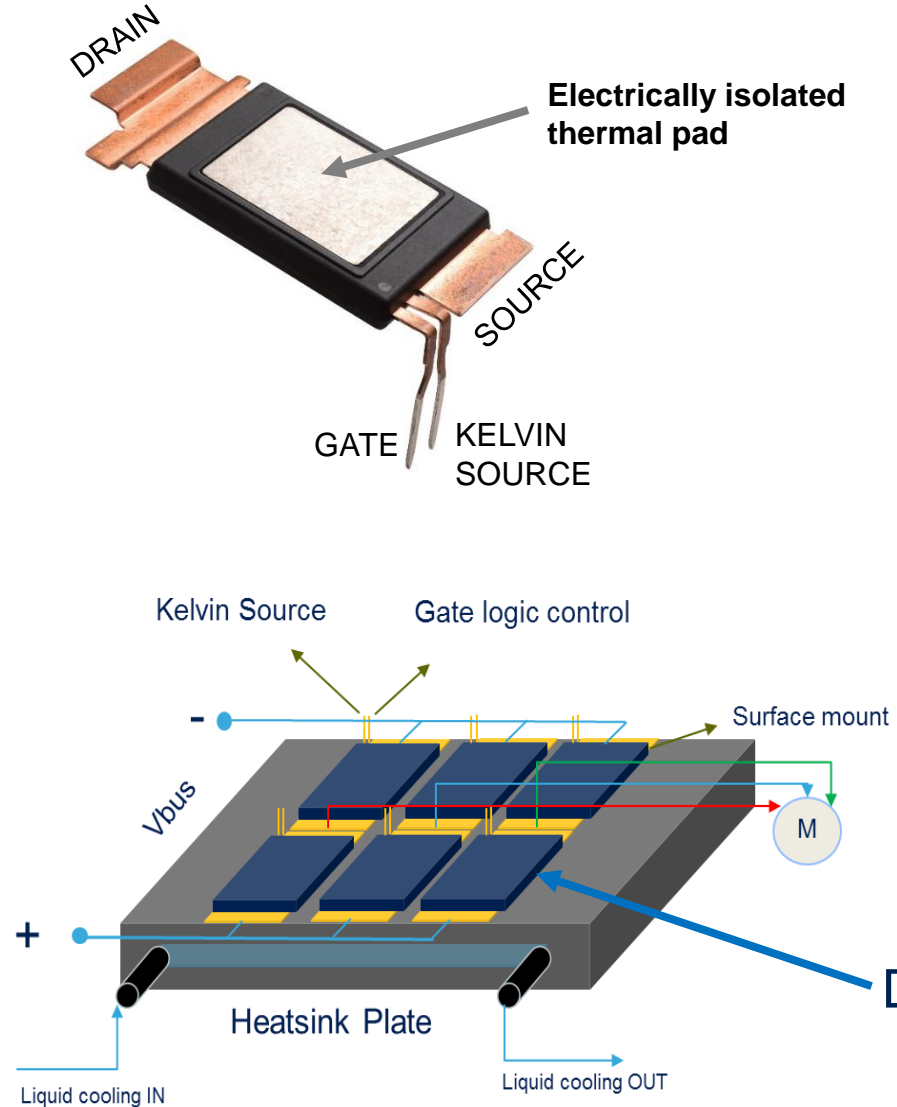
## Latest advances:

- new discrete power package
- advanced isolated gate driver

# STPAK™: Multi Sintering Package

## Ideal for Electric Vehicle applications

31



- Multi sintering solution for better thermal performance and higher reliability
- Low inductance connection to bus bar
- Kelvin source pin
- AEC-Q101 qualified, 175°C Maximum  $T_j$
- Suitable for both SiC MOSFET and IGBT
- 650V and 1200V rated

Direct sintering to the bottom of the heatsink

# STGAP1AS: advanced galvanically isolated gate driver

32

AEC-Q100

Wide operating range ( $T_A$  -40°C to +125°C)

5 A sink/source current

High Voltage Rail up to 1.5 kV

Wide drive voltage range (+ 36 V / -10V)

Short propagation delay

100 ns typ.; 130 ns max over temperature

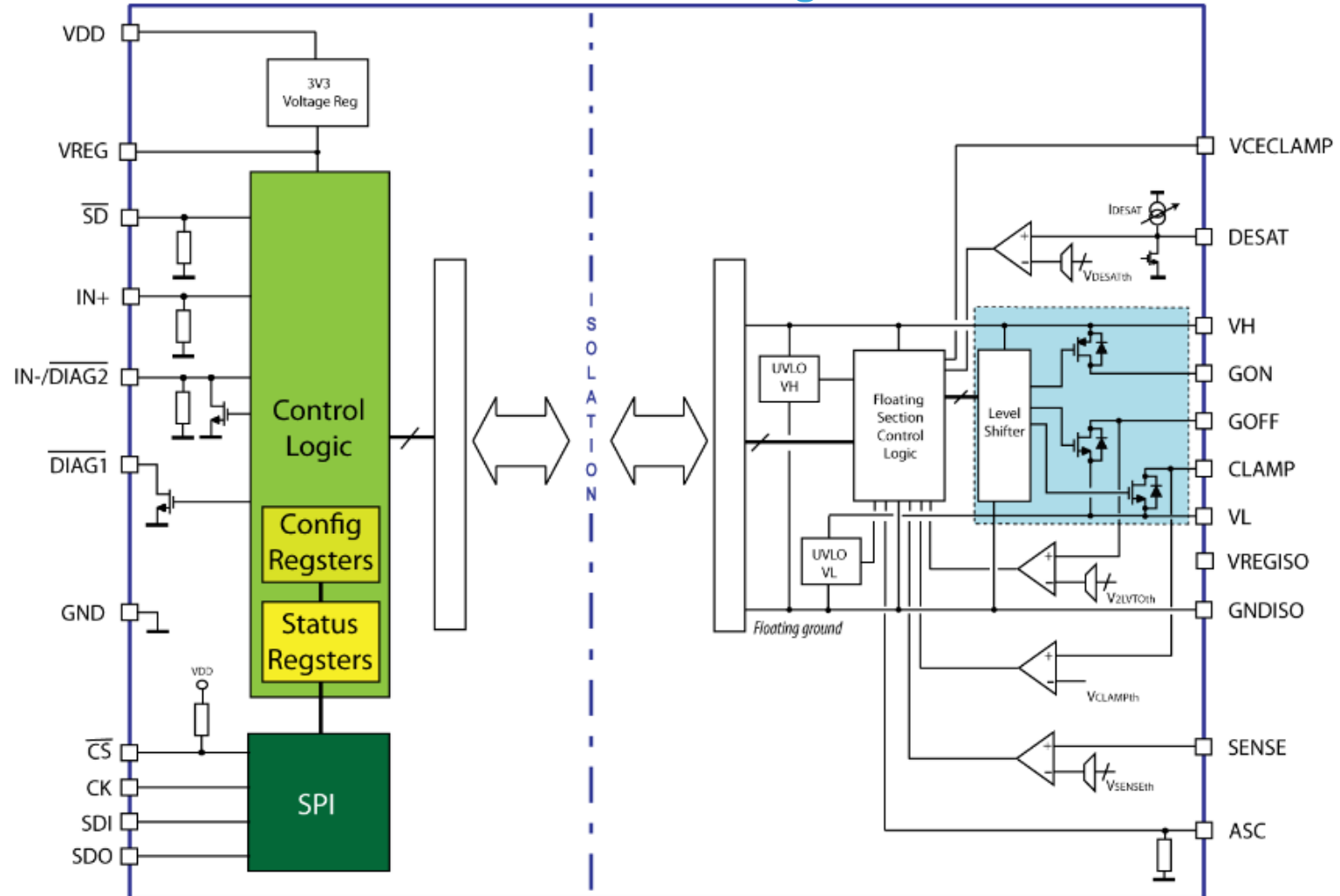
Excellent CMTI rating

50 V/ns across full temperature range

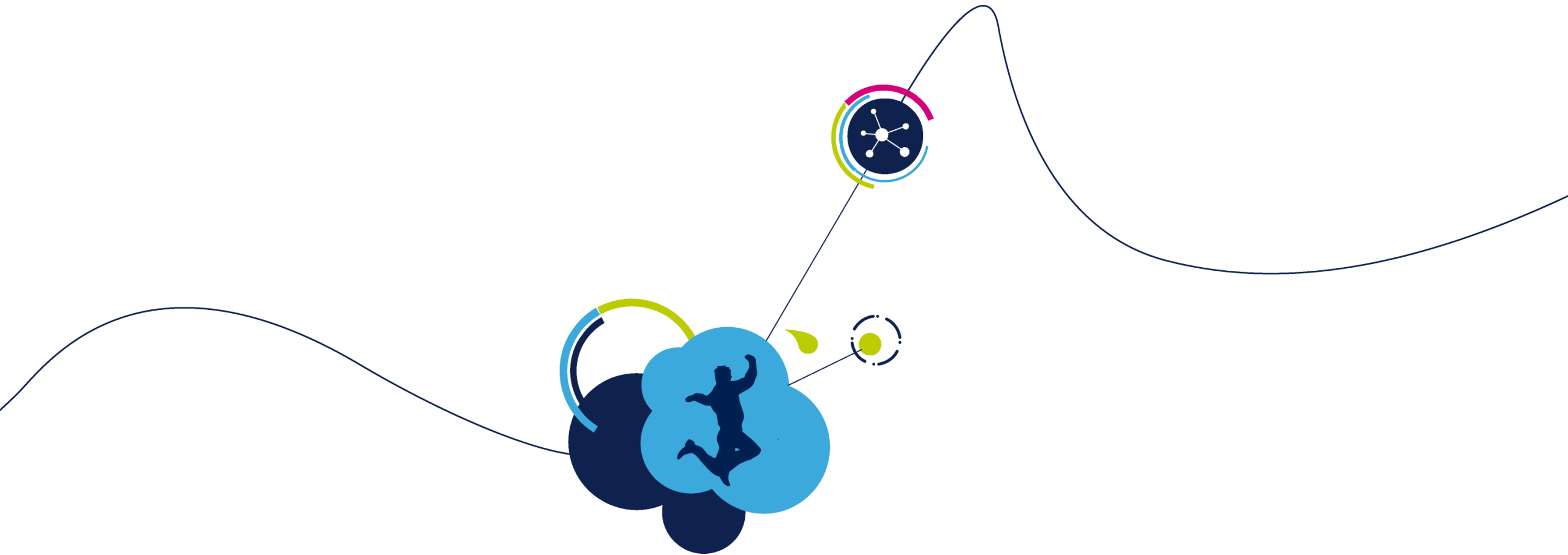
Advanced features

5A Active Miller clamp, Desaturation detection, 2-level turn-off, VCEClamp, ASC

STGAP1AS Block Diagram

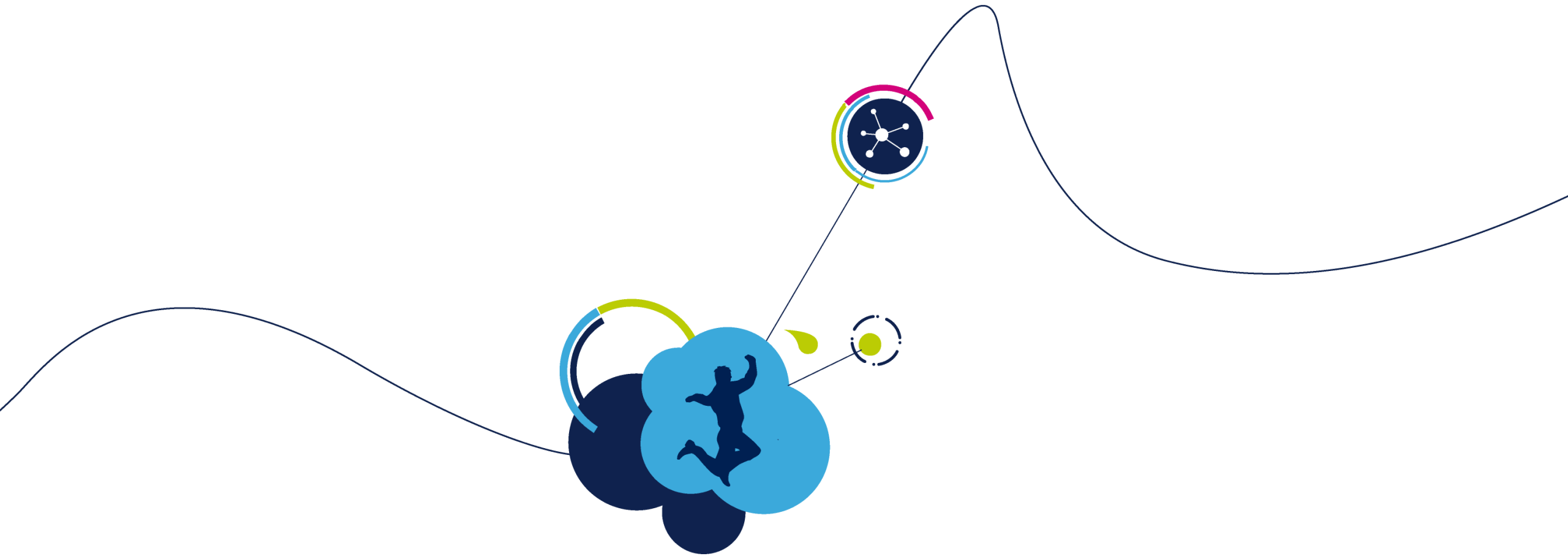






# Conclusions

- SiC MOSFET-based power converters now offer system level benefits compared to silicon IGBT-based solutions
  - Traction inverter example shows how SiC can improve reliability and reduce system level cost
- SiC MOSFETs provide reduced footprint today compared to silicon based solutions and further footprint reductions are still possible
- Higher volume use and further innovation of SiC will continue to push down the cost and further displace silicon power transistors in the future



Thank You!